IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Previously Presented): A multilayer printed wiring board comprising:

a core substrate;

a first conductor layer having a plurality of conductor circuits formed on said core substrate;

an interlayer insulating layer formed over said first conductor layer and said core substrate;

a second conductor layer having a plurality of conductor circuits formed on said interlayer insulating layer; and

a via hole structure electrically connecting one of said conductor circuits of said first conductor layer and one of said conductor circuits of said second conductor layer,

wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said interlayer insulating layer, and

wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and $\alpha 1$ and $\alpha 2$ satisfy $\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 2 (Canceled).

Claim 3 (Previously Presented): The multilayer printed wiring board according to claim 1, wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and said $\alpha 1$ satisfies $2\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 4 (Currently Amended): The multilayer printed wiring board according to claim 1, wherein the first conductor layer on said core substrate comprises a power supply layer or an earth.

Claim 5 (Previously Presented): The multilayer printed wiring board according to claim 1, further comprising a capacitor mounted over said second conductor layer.

Claim 6 (Previously Presented): A multilayer printed wiring board comprising:

a core substrate comprising a multilayer core substrate comprising not less than three layers including at least one inner conductor layer having a plurality of conductor circuits;

a conductor layer having a plurality of conductor circuits formed over said core substrate;

an interlayer insulating layer formed over said conductor layer and said core substrate; and

a through hole structure formed through said interlayer insulating layer and electrically connecting one of said conductor circuits of said at least one inner conductor layer and one of said conductor circuits of said conductor layer formed over said core substrate,

wherein the at least one inner conductor layer of said core substrate and the conductor layer over said core substrate include a power supply layer or an earth,

wherein said at least one inner conductor layer of said core substrate comprises the power supply layer or the earth, and said conductor layer is formed on a surface of said core substrate and comprises a signal line, and

wherein the at least one inner conductor layer of said core substrate has a thickness which is larger than a thickness of the conductor layer formed over the surface of said core substrate.

Claims 7-8 (Canceled).

Claim 9 (Previously Presented): The multilayer printed wiring board according to claim 6, wherein the at least one inner conductor layer of said core substrate comprises not less than two inner conductor layers.

Claim 10 (Previously Presented): The multilayer printed wiring board according to claim 6, wherein said core substrate comprises an electrically isolated metallic plate, and a plurality of insulating layers formed on surfaces of said electrically isolated metallic plate, respectively, said at least one inner conductor layer of said core substrate comprises a plurality of inner conductor layers, and the inner conductor layers are formed on the insulating layers, respectively.

Claim 11 (Previously Presented): The multilayer printed wiring board according to claim 6, wherein the conductor layer is formed on a surface of said core substrate, and said at least one inner layer of said core substrate has a thickness which is larger than a thickness of the conductor layer formed on the surface of said core substrate.

Claim 12 (Currently Amended): The multilayer printed wiring board according to claim [[2]] 1, wherein the first conductor layer formed on said core substrate comprises a power supply layer or an earth.

Claim 13 (Currently Amended): The multilayer printed wiring board according to claim [[2]] 1, further comprising a capacitor mounted over a surface of said core substrate.

Claim 14 (Previously Presented): A multilayer printed wiring board according to claim 6, wherein said at least one inner layer of said core substrate has a thickness which is larger than a thickness of the conductor layer formed on said core substrate.

Claim 15 (Previously Presented): The multilayer printed wiring board according to claim 6, wherein said at least one inner conductor layer of said core substrate comprises not less than two inner conductor layers.

Claim 16 (Previously Presented): The multilayer printed wiring board according to claim 6, wherein said core substrate comprises an electrically isolated metallic plate and a plurality of insulating layers formed on surfaces of said electrically isolated metallic plate, respectively, said at least one inner conductor layer of said core substrate comprises a plurality of inner conductor layers, and the inner conductor layers are formed on the insulating layers, respectively.

Claim 17 (Previously Presented): The multilayer printed wiring board according to claim 6, further comprising a second conductor layer having a plurality of conductor circuits formed over said interlayer insulating layer, wherein said conductor layer is formed on a surface of said core substrate, said at least one inner layer of said core substrate has a thickness which is larger than a thickness of the conductor layer formed on the surface of said core substrate, and the thickness of said conductor layer formed on the surface of said core substrate is larger than a thickness of said second conductor layer.

Claim 18 (Previously Presented): A multilayer printed wiring board comprising:

a core substrate; and

a multilayered structure formed on said core substrate and including a first conductor layer having a plurality of conductor circuits formed on said core substrate, at least one interlayer insulating layer formed over said first conductor layer, and a second conductor layer having a plurality of conductor circuits formed on said at least one interlayer insulating layer,

wherein said first conductor layer on said core substrate has a thickness which is larger than a thickness of said second conductor layer on said at least one interlayer insulating layer, and

wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and $\alpha 1$ and $\alpha 2$ satisfy $\alpha 2 < \alpha 1 < 40\alpha 2$.

Claim 19 (Canceled).

Claim 20 (Previously Presented): The multilayer printed wiring board according to claim 18, wherein said thickness of said first conductor layer on said core substrate is $\alpha 1$, said thickness of said second conductor layer on said interlayer insulating layer is $\alpha 2$, and said $\alpha 1$ satisfies $2\alpha 2 < \alpha 1 < 40\alpha 2$.